

FALIT FS Laser Decapsulation System



Capability/Application

Laser decapsulation is a technique which can locally remove the molding material without damaging the overall functionality of the chip. Compared to chemical decapsulation technique, Laser decapsulation is more efficient and reduce the exposure to strong acid etching environments.

Specifications

Cross-section Laser Cut module:

Model: Draco-51S40A Green Laser

Wavelength: 532nm

Average Output Power: >10W at 40kHz

Pulse Width: <30ns at 30kHz

Laser Decap module:

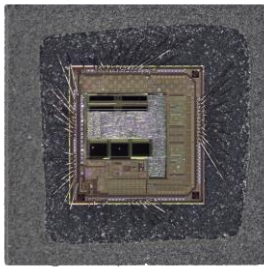
Model: Harrier-1064-14-L-V3 IR laser

Wavelength: 1064nm

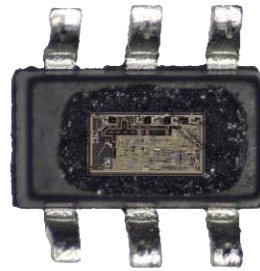
Average Output Power: >12W at 10KHz

Pulse Width: <40ns at 10KHz

Example application images



5x5 QFN decapsulation



SOT23-6 decapsulation

Equipment manufacturer web page

<https://www.controllaser.com/products/falit-failure-analysis-laser-inspection-tools-for-laser-decap-cross-sectioning-delidding/#one>

Youtube demo videos

https://www.youtube.com/watch?v=LIb__2FrT4s